Bonding with

WaferGrip Thin Film Adhesive

vs.

Wax

Bonding with Wax

Bonding wafer to carriers with wax is a traditional method of mounting wafers for the saw dicing process. It is a very messy process that is extremely operator dependent. The technique involves heating up the carrier to the exact temperature, then melting the wax onto it by hand. The operator works the wax around until it covers the carrier. Once the wax is in place the wafer is then "smushed" onto the wax and pushed around in an attempt to remove the air pockets from under the wafer. Any air pockets not removed by this process will significantly jeopardize the dicing process.

Bonding with WaferGrip

The modern day alternative to the wax process is to use WaferGrip. WaferGrip is a preformed adhesive available in many sizes and comes precut to fit the wafers. To make the bond, the operator simply makes a stack of the substrate, WaferGrip and the wafer. The stack is then placed in the Dynatex DXB bonder. The bonder executes a predetermined bonding process and the job is complete. It is a process that is operator independent and produces a wafer carrier stack with very low TTV.

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